

ABSTRACT

A method and device are provided to realize a structure in which different kinds of chips are three-dimensionally mounted while suppressing the deterioration of the connection reliability. A semiconductor package PK12 in which a semiconductor chip 13 is sealed with a sealing resin 17 is stacked on a semiconductor package PK11 in which a semiconductor chip 3 is mounted on a carrier substrate 1 by anisotropic conductive film (ACF) bonding. The range in which the semiconductor chip 13 is sealed with a sealing resin 17 is set so as to cover the semiconductor chip 13 and to be attached to the region for arranging the protruding electrodes 16 on the side of the surface on which the semiconductor chip 13 is mounted.